

designers and manufacturers of the new Hayes-compatible Multi-function V22 bis Quattro Modem, and already received advance orders for 2,000 units, even before its production at Compec 85.

### BEST SELLER

"Quattro is a 'best seller,'" says Bob Jones, General Manager of Dowty Information Systems. "It is the complete modem in a single package."

Quattro received BAPT approval near record-breaking time

## Electronic first

The Interconnect Division of Dowty Electronic Components has launched its first electronic switching products, a range of programmable switches known as the PS Series. Housed in industry-standard DIL packages, the devices offer from two to twelve SPST contacts, as well as twelve SPST contacts, modules per package.

## Dowty launches into the consumer market

DOWTY Information Systems, part of Dowty Electronics Division,

# CHIPRACK WINS FOR DOWTY ELECTRONIC COMPONENTS

CHIPRACK, the revolutionary new chip interconnection product developed by Dowty Electronic Interconnect, won a major design award sponsored by "Electronics Weekly" at the recent Internecon '85 exhibition. It was judged to be the most innovative electro-mechanical product of the year.

Brian Shorrock, Managing Director of Dowty Electronic Components Limited received the award from the opposition spokesman for Trade and Industry, John Smith, at the Internecon Awards Dinner in Brighton.

### 3D DESIGN

Chiprack was designed as a three-dimensional system for interconnecting very large scale integrated (V.L.S.I.) products packaged in the 'leadless chip' style. The system obviates the need for costly, custom designed, multilayer printed circuit boards by enabling complex three-dimensional interconnection patterns to be achieved within and between Chiprack structures.

Chiprack offers high packaging densities and was displayed as a functioning unit at the Internecon '85 exhibition.

The product is at the pre-production stage and will be launched in production form

Brian Shorrock, Managing Director of Dowty Electronic Components Limited, receiving the award for the "Most Innovative Electro-mechanical Product of the Year" on behalf of DEI from the Opposition Spokesman for Trade and Industry, John Smith (left), at the Internecon Awards Dinner in Brighton. Looking on is Mike Elliott, Editor of "Electronics Weekly", which sponsored the award won by "Chiprack".

